

As illustrated in Fig. 7C, the VDD wire 26b formed in the pad area 13 is electrically connected to the VDD wire 26a formed in the input/output area 12 through a first electrical connector 28. Similarly, as illustrated in Fig. 7B, the GND wire 27b formed in the pad area 13 is electrically connected to the GND wire 27a formed in the input/output area 12 through a second electrical connector 29.

Please delete the paragraph bridging pages 16 and 17 and replace it with the following:

In accordance with the second embodiment, the bypass capacitor could have an increased capacity, because an additional capacity is defined between the teeth of the VDD wire 26b and teeth of the GND wire 27b.

Please delete the fifth full paragraph on page 17 and replace it with the following:

The protection device 31 is comprised of a substrate 20 formed at a surface with a n-type well 32a and a p-type well 32b, a first interlayer insulating film 20a formed on the substrate 20, a first layer 20b formed on the first interlayer insulating film 20a, a second interlayer insulating film 20c formed on the first layer 20b, and a second signal wiring layer 33 formed on the second interlayer insulating film 20c.

IN THE CLAIMS:

Please enter the following amended claims: